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Dated: March 19, 2002 Signature: *[Signature]*

(Kimberly V. Perry)

Docket No.: TESSERA 3.3-018 CONT CONT II CONT II CONT II (PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Khandros et al.

Application No.: 09/691,807

Filed: October 19, 2000

For: STACKED CHIP ASSEMBLY



Group Art Unit: 2815

Examiner: S. Clark

9/B
4-21-02
Kayton

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Dear Sir:

In response to the Official Action mailed December 19, 2001, in which Claims 2-32 and 52-62 were allowed, Claim 33 was rejected, and Claims 34-51 were objected to, Applicants present the following amendments and remarks.

IN THE CLAIMS

CLEAN COPY OF AMENDED CLAIMS:

32-4 34. (Amended) A semiconductor chip assembly comprising:

(a) a first semiconductor chip having a front surface, a rear surface and contacts on said front surface;

(b) a substrate having contact pads thereon, said substrate extending beneath the rear surface of the first semiconductor chip so that said front surface of said first semiconductor chip faces upwardly away from said substrate, at least some of said contacts on said first semiconductor chip

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